

# SPECIFICATION FOR LCD MODULE

**MODULE NO: YB-TG240320S29A-N-A0**

**Doc.Version:01**

Customer Approval:

<input type="checkbox"/> Accept	<input type="checkbox"/> Reject
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YEEBO	NAME	SIGNATURE	DATE
Prepare	Electronic Engineer	任玉琛	2018/6/7
Check	Mechanical Engineer	[Signature]	2018/6/7
Verify		邵茗刚	2018/6/7
Approval		[Signature]	2018/6/7

APPROVAL FOR SPECIFICATIONS ONLY

APPROVAL FOR SPECIFICATIONS AND SAMPLE

WIMRD005-02-D



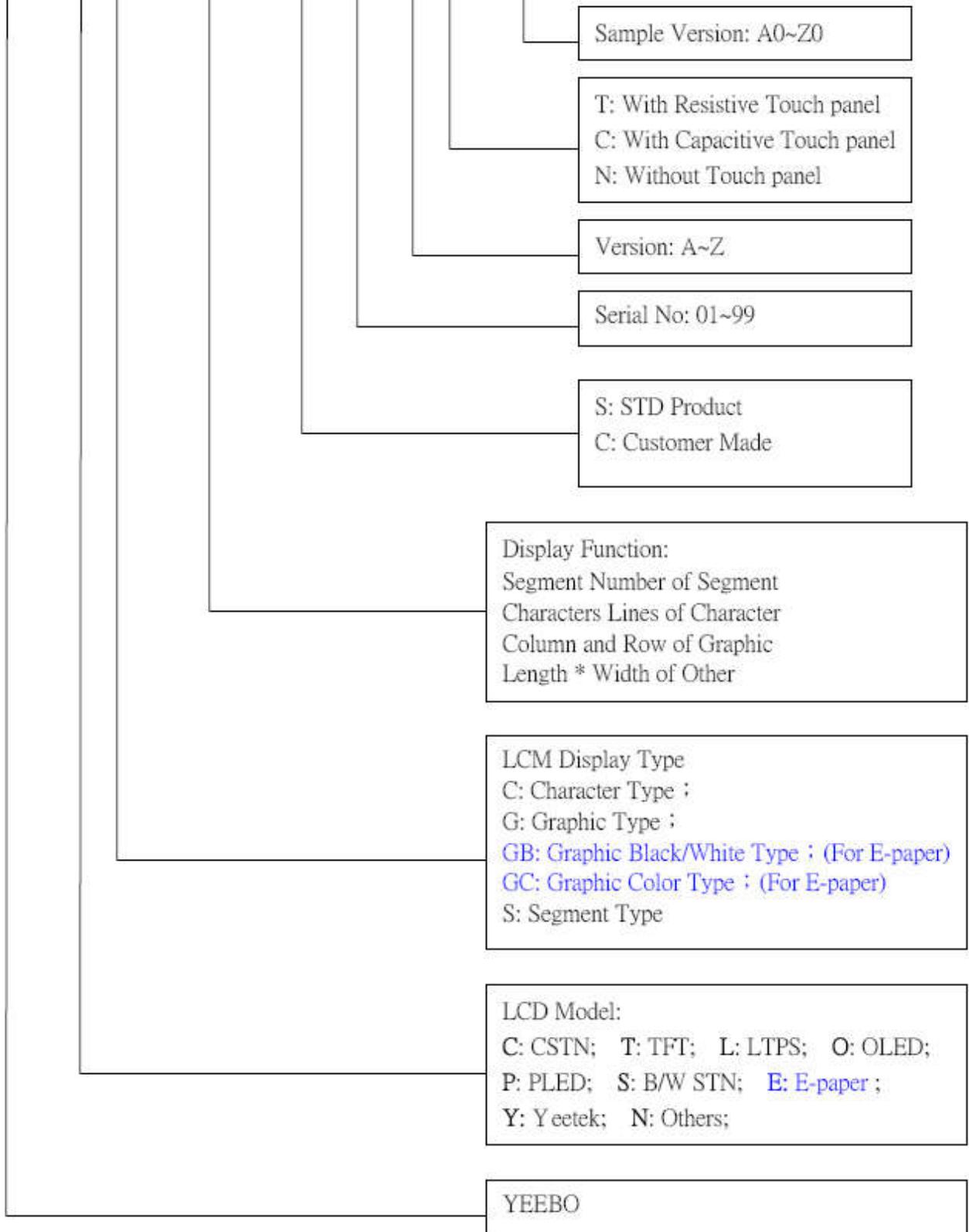
## **2. Table of Contents:**

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### 3. Module Numbering System:

(Example)

**YB-TG240320S01D-T-A0**

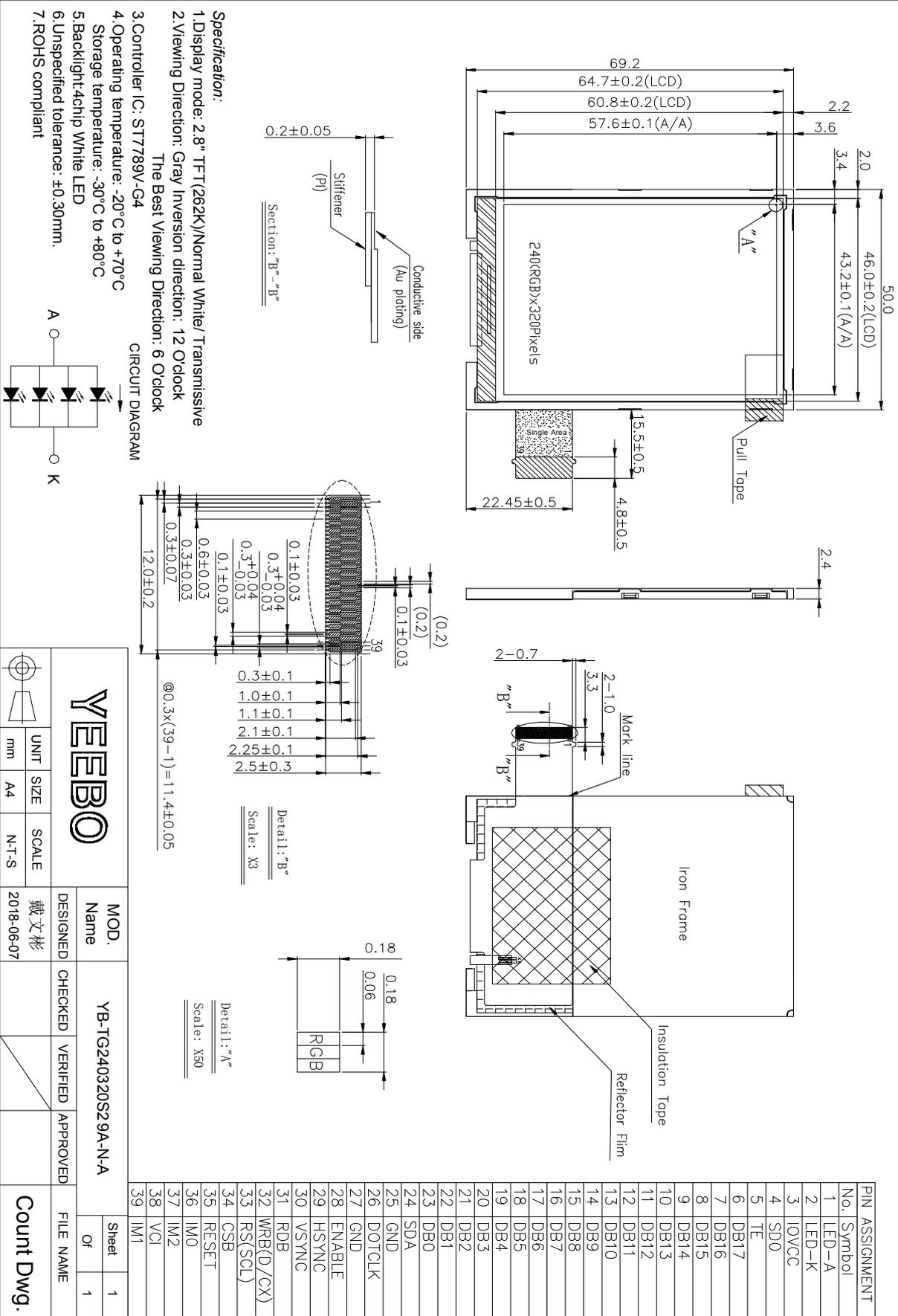


#### **4. General Specification:**

ITEM	CONTENTS
Module Size	50.0 (W)* 69.2(H)* 2.4(T)mm
Module Size(With FPC)	65.5(W)* 69.2(H)* 2.4(T)mm
Display Size(Diagonal)	2.8 inch
Display Format	240(RGB)*320 Pixels
Active Area	43.2(W) * 57.6(H) mm
Pixel Pitch	0.18 * 0.18 mm
LCD Type	TFT(65K) / Transmissive / NW/ <b>Anti-Glare</b>
View Direction (Gray Inversion)	12:00 O'clock
The Best Viewing Direction:	6:00 O'clock
Controller IC	ST7789V
Weight	14.2g

## 5. LCM drawing:

Count drawing & Spec. revision record during discussion with customer		Rec.	Date
Revision content description		FIRST ISSUE	2018-03-28
#1	Cancel JET-INK CODE		
#2			2018-06-07



## 6. Electrical Characteristics

### 6-1 Absolute Maximum Ratings

(Ta=25°C VSS=0V)

Item	Symbol	Min.	Type	Max.	Unit	Remark
Supply Voltage	VDD	-0.3	-	+4.6	Volt	Note1
Supply Voltage(Logic)	VDDI	-0.3	-	+4.6	Volt	Note1
Operating Temperature	Topr	-20	-	+70	°C	-
Storage Temperature	Tstg	-30	-	+80	°C	-

Note1: Absolute maximum rating is the limit value beyond which the IC maybe broken.  
They do not assure operations.

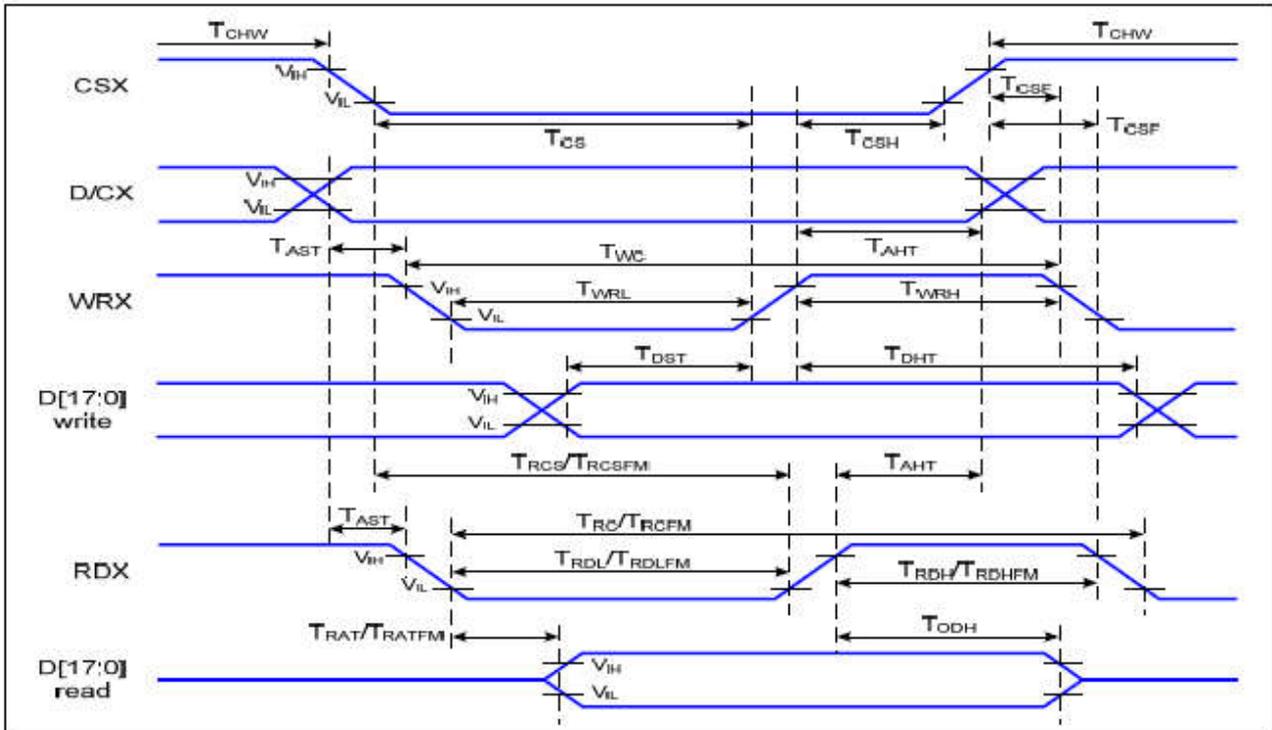
### 6-2 Operating Conditions

(Ta=25°C )

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Power Supply voltage	VDD	-	2.4	2.8	3.3	Volt
Supply voltage for I/O	VDDI	-	1.65	1.8	3.3	Volt
Input Voltage	V <sub>IH</sub>	-	0.7 * VDDI	-	VDDI	v
	V <sub>IL</sub>	-	GND	-	0.3* VDDI	v
Power Supply Current for LCM	IDD	VDD=2.8V	-	7	10.5	mA

### 6-3 Timing Characteristics

#### 8080 Series MCU Parallel Interface Characteristics: 18/16/9/8-bit Bus

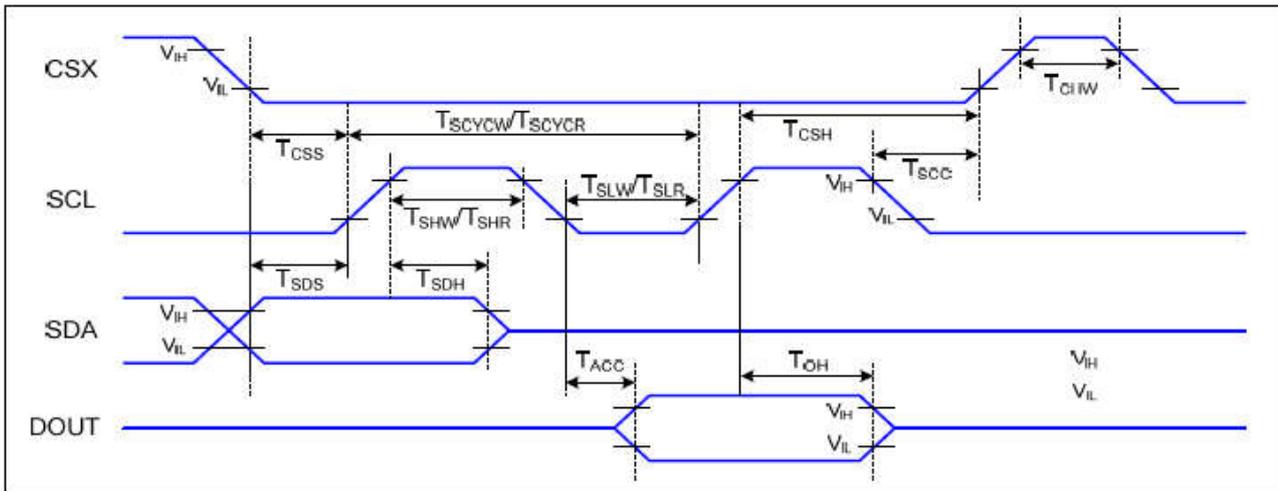


Parallel Interface Timing Characteristics (8080-Series MCU Interface)

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta= -30 to 70 °C

Signal	Symbol	Parameter	Min	Max	Unit	Description
D/CX	T <sub>AST</sub>	Address setup time	0		ns	
	T <sub>AHT</sub>	Address hold time (Write/Read)	10		ns	
CSX	T <sub>CHW</sub>	Chip select "H" pulse width	0		ns	
	T <sub>CS</sub>	Chip select setup time (Write)	15		ns	
	T <sub>RCS</sub>	Chip select setup time (Read ID)	45		ns	
	T <sub>RCSFM</sub>	Chip select setup time (Read FM)	355		ns	
	T <sub>CSF</sub>	Chip select wait time (Write/Read)	10		ns	
	T <sub>CSH</sub>	Chip select hold time	10		ns	
WRX	T <sub>WC</sub>	Write cycle	66		ns	
	T <sub>WRH</sub>	Control pulse "H" duration	15		ns	
	T <sub>WRL</sub>	Control pulse "L" duration	15		ns	
RDX (ID)	T <sub>RC</sub>	Read cycle (ID)	160		ns	When read ID data
	T <sub>RDH</sub>	Control pulse "H" duration (ID)	90		ns	
	T <sub>RDL</sub>	Control pulse "L" duration (ID)	45		ns	
RDX (FM)	T <sub>RCFM</sub>	Read cycle (FM)	450		ns	When read from frame memory
	T <sub>RDHFM</sub>	Control pulse "H" duration (FM)	90		ns	
	T <sub>RDLFM</sub>	Control pulse "L" duration (FM)	355		ns	
D[17:0]	T <sub>DST</sub>	Data setup time	10		ns	For CL=30pF

Serial Interface Characteristics (3-line serial):

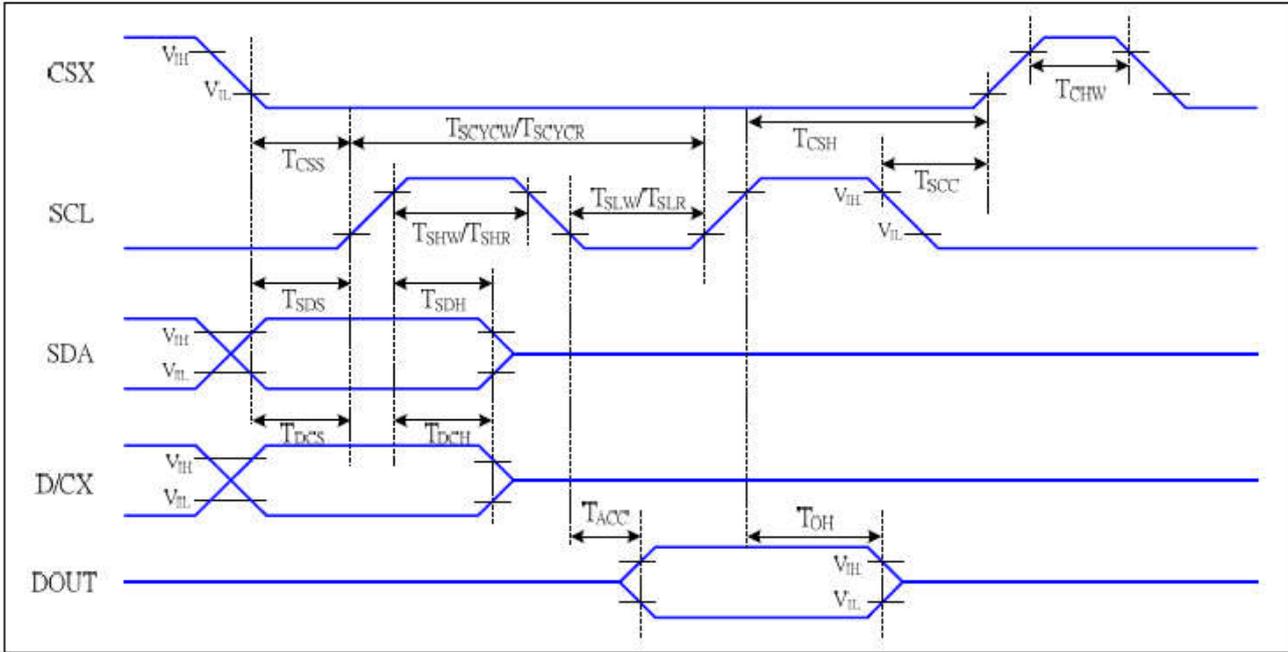


3-line serial Interface Timing Characteristics

V<sub>DDI</sub>=1.65 to 3.3V, V<sub>DD</sub>=2.4 to 3.3V, A<sub>GN</sub>D=D<sub>GN</sub>D=0V, T<sub>a</sub>=-30 to 70 °C

Signal	Symbol	Parameter	Min	Max	Unit	Description
CSX	T <sub>CSS</sub>	Chip select setup time (write)	15		ns	
	T <sub>CSH</sub>	Chip select hold time (write)	15		ns	
	T <sub>CSS</sub>	Chip select setup time (read)	60		ns	
	T <sub>SCC</sub>	Chip select hold time (read)	65		ns	
	T <sub>CHW</sub>	Chip select "H" pulse width	40		ns	
SCL	T <sub>SCYCW</sub>	Serial clock cycle (Write)	66		ns	
	T <sub>SHW</sub>	SCL "H" pulse width (Write)	15		ns	
	T <sub>SLW</sub>	SCL "L" pulse width (Write)	15		ns	
	T <sub>SCYCR</sub>	Serial clock cycle (Read)	150		ns	
	T <sub>SHR</sub>	SCL "H" pulse width (Read)	60		ns	
	T <sub>SLR</sub>	SCL "L" pulse width (Read)	60		ns	
SDA (DIN)	T <sub>SDS</sub>	Data setup time	10		ns	
	T <sub>SDH</sub>	Data hold time	10		ns	
DOUT	T <sub>ACC</sub>	Access time	10	50	ns	For maximum CL=30pF
	T <sub>OH</sub>	Output disable time	15	50	ns	For minimum CL=8pF

**Serial Interface Characteristics (4-line serial):**

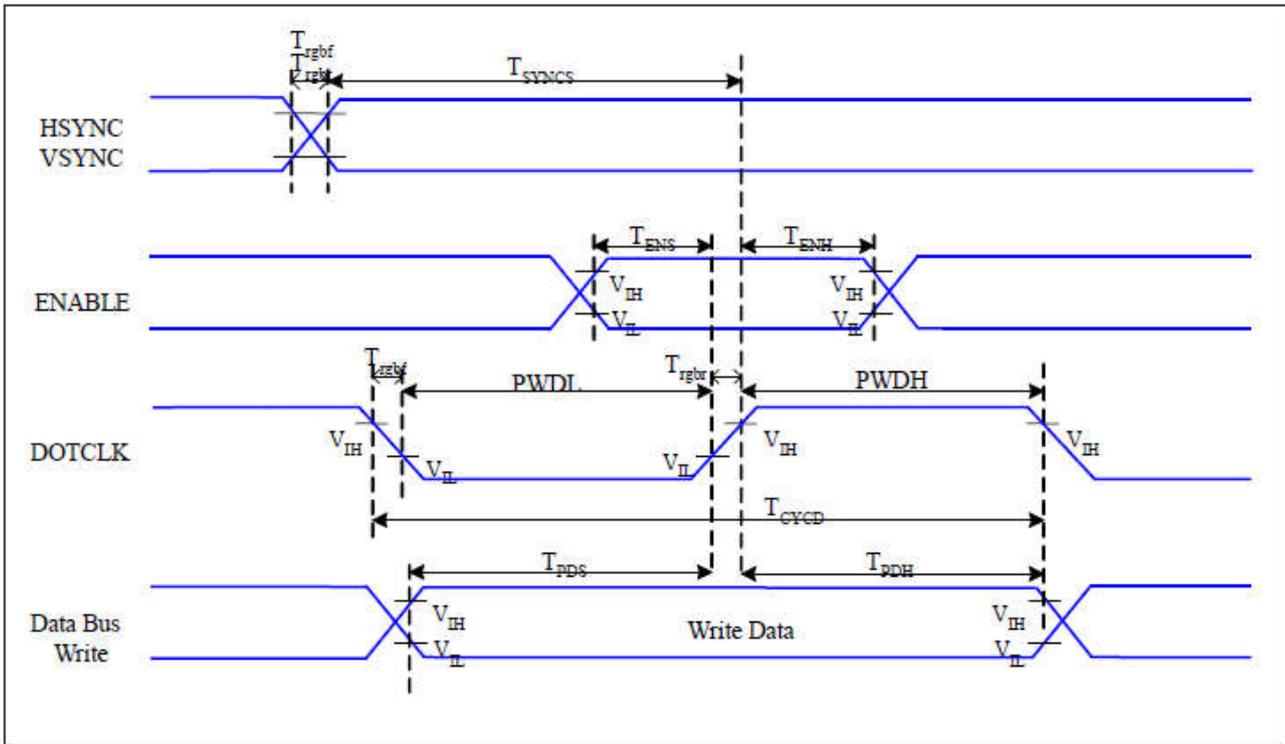


**4-line serial Interface Timing Characteristics**

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=-30 to 70 °C

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
CSX	$T_{CSS}$	Chip select setup time (write)	15		ns	
	$T_{CSH}$	Chip select hold time (write)	15		ns	
	$T_{CSS}$	Chip select setup time (read)	60		ns	
	$T_{SCC}$	Chip select hold time (read)	65		ns	
	$T_{CHW}$	Chip select "H" pulse width	40		ns	
SCL	$T_{SCYCW}$	Serial clock cycle (Write)	66		ns	-write command & data ram
	$T_{SHW}$	SCL "H" pulse width (Write)	15		ns	
	$T_{SLW}$	SCL "L" pulse width (Write)	15		ns	
	$T_{SCYCR}$	Serial clock cycle (Read)	150		ns	-read command & data ram
	$T_{SHR}$	SCL "H" pulse width (Read)	60		ns	
	$T_{SLR}$	SCL "L" pulse width (Read)	60		ns	
D/CX	$T_{DCS}$	D/CX setup time	10		ns	
	$T_{DCH}$	D/CX hold time	10		ns	
SDA (DIN)	$T_{SDS}$	Data setup time	10		ns	
	$T_{SDH}$	Data hold time	10		ns	
DOUT	$T_{ACC}$	Access time	10	50	ns	For maximum CL=30pF
	$T_{OH}$	Output disable time	15	50	ns	For minimum CL=8pF

RGB Interface Characteristics:



RGB Interface Timing Characteristics

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=-30 ~ 70 °C

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
HSYNC, VSYNC	$T_{SYNCS}$	VSYNC, HSYNC Setup Time	30	-	ns	
ENABLE	$T_{ENS}$	Enable Setup Time	25	-	ns	
	$T_{ENH}$	Enable Hold Time	25	-	ns	
DOTCLK	PWDH	DOTCLK High-level Pulse Width	60	-	ns	
	PWDL	DOTCLK Low-level Pulse Width	60	-	ns	
	$T_{CYCD}$	DOTCLK Cycle Time	120	-	ns	
	Trghr, Trghf	DOTCLK Rise/Fall time	-	20	ns	
DB	$T_{PDS}$	PD Data Setup Time	50	-	ns	
	$T_{PDH}$	PD Data Hold Time	50	-	ns	

18/16 Bits RGB Interface Timing Characteristics

## 7. Optical Characteristics:

Item	Symbol	Conditions	Specifications			Unit	Note	
			Min	Typ	Max			
Transmittance (With PL)	T(%)	-	-	6.4	-	-	-	
Contrast Ratio	CR	$\Theta = 0$ Normal Viewing angle	-	500	-	-	(1) (2)	
Response time	TR+TF	-	-	16		ms	(1) (3)	
Viewing angle	Hor.	$\Theta_{x+}$	CR $\geq 10$	-	70	-	deg.	-
		$\Theta_{x-}$		-	70	-		
	Ver.	$\Theta_{y+}$		-	70	-		
		$\Theta_{y-}$		-	60	-		

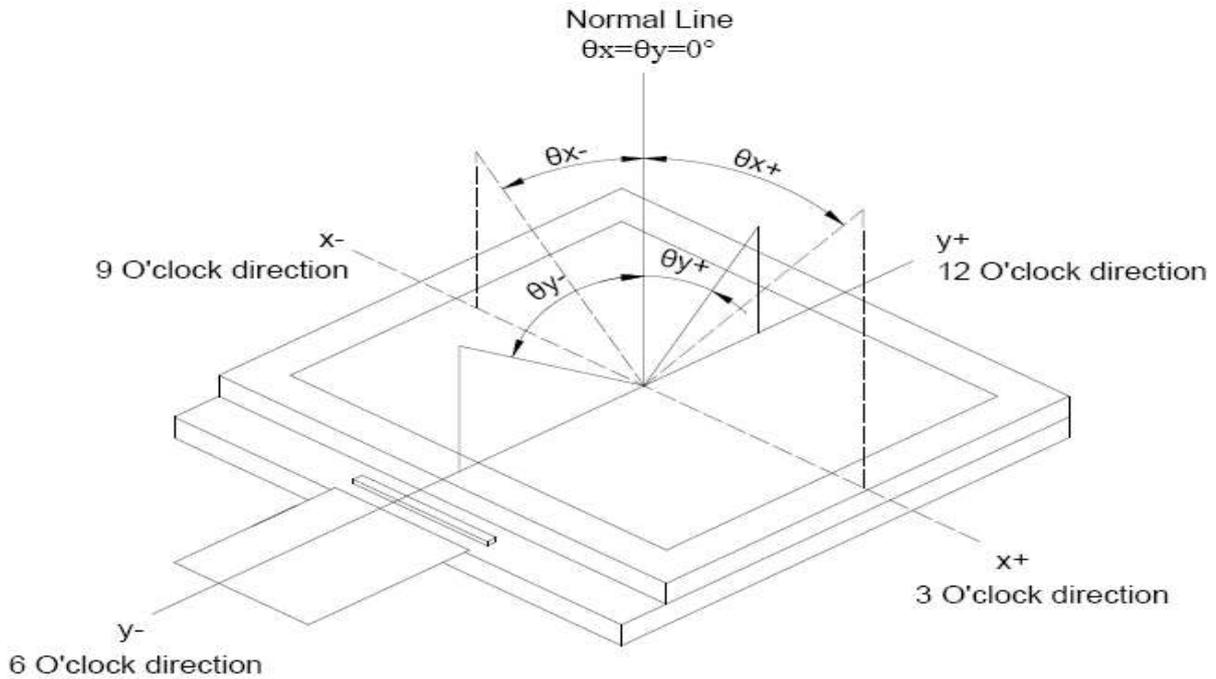
### Measuring Condition

1. Measuring surrounding: dark room
2. Ambient temperature:  $25 \pm 2^\circ\text{C}$
3. 30 min. Warm-up time.

### Color of CIE Coordinate:

Item		Symbol	Condition	Min.	Typ.	Max.
Chromaticity Coordinates (Transmissive)	Red	x	$\theta = \phi = 0^\circ$ LED Backlight	0.5313	0.5813	0.6313
		y		0.2889	0.3389	0.3889
	Green	x		0.287	0.337	0.387
		y		0.5468	0.5968	0.6468
	Blue	x		0.0967	0.1467	0.1967
		y		0.0527	0.1027	0.1527
	White	x		0.2231	0.2731	0.3231
		y		0.2446	0.2946	0.3446

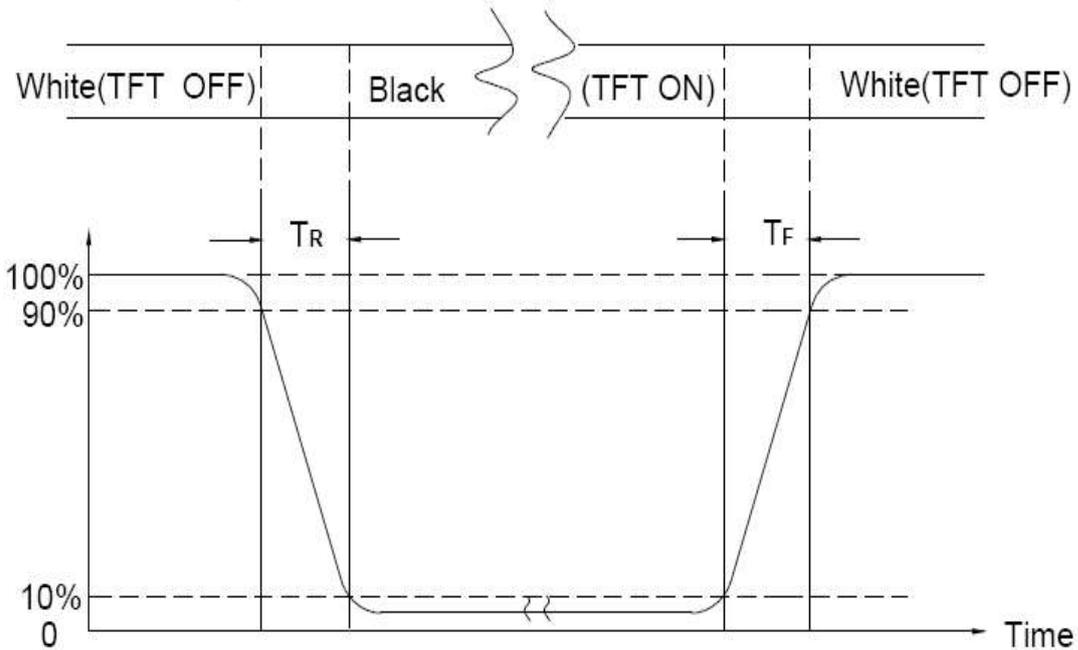
Note (1) Definition of Viewing Angle :



Note (2) Definition of Contrast Ratio(CR) :  
measured at the center point of panel

$$\text{Contrast ratio (CR)} = \frac{\text{Photo detector output when LCD is at "White" state}}{\text{Photo detector output when LCD is at "Black"}}$$

Note (3) Definition of Response Time : Sum of  $T_R$  and  $T_F$



## **8. Interface Pin Assignment:**

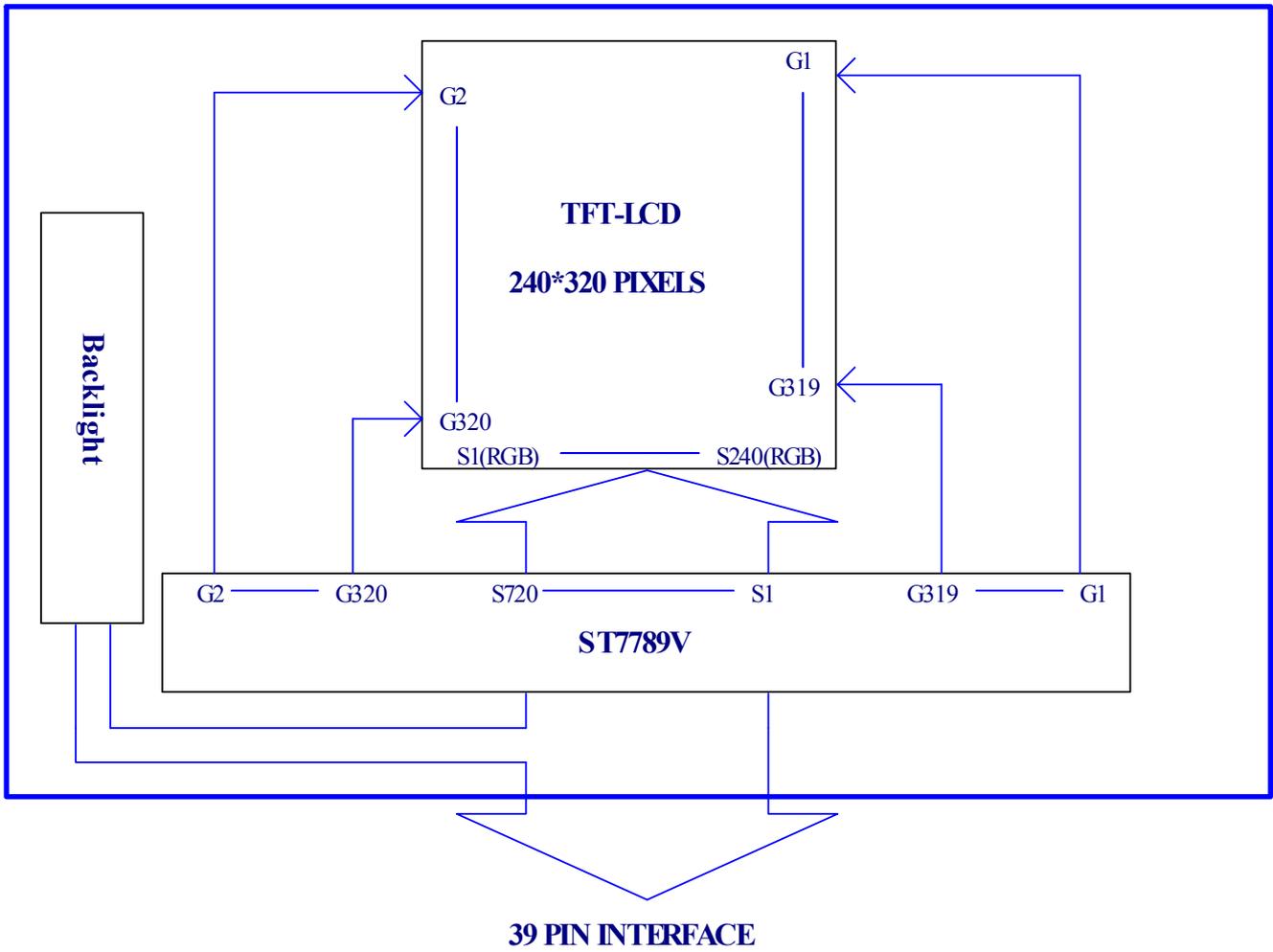
No.	Symbol	Function
1	LED_A	LED power anode
2	LED_K	LED power cathode
3	IOVCC	Digital power supply
4	SDO	Serial data output signal
5	TE	Tearing effect output pin (No connection)
6	DB17	Data bus
7	DB16	Data bus
8	DB15	Data bus
9	DB14	Data bus
10	DB13	Data bus
11	DB12	Data bus
12	DB11	Data bus
13	DB10	Data bus
14	DB9	Data bus
15	DB8	Data bus
16	DB7	Data bus
17	DB6	Data bus
18	DB5	Data bus
19	DB4	Data bus
20	DB3	Data bus
21	DB2	Data bus
22	DB1	Data bus
23	DB0	Data bus
24	SDA	Serial data input signal
25	GND	Ground
26	DOTCLK	Pixel clock signal in RGB I/F mode
27	GND	Ground

28	ENABLE	Data enable signal in RGB I/F mode
29	HSYNC	Horizontal sync. Signal in RGB I/F mode
30	VSYNC	Vertical sync. Signal in RGB I/F mode
31	RDB	Read signal in 80-series parallel interface
32	WRB	Write signal in 80-series parallel interface
33	RS	Data/Command select signal
34	CSB	Chip select signal
35	RESET	Reset signal
36	IM0	Select MCU Interface mode
37	IM2	Select MCU Interface mode
38	VCI	Analog power supply
39	IM1	Select MCU Interface mode

The MCU interface mode select.:

IM2	IM1	IM0	MCU-Interface Mode	Data pin
0	0	0	80-16bit parallel I/F II	D[17:0] D[8:1]
0	0	1	80-8bit parallel I/F II	DB[17:10]
0	1	0	80-18bit parallel I/F II	DB[17:0]
0	1	1	80-9bit parallel I/F II	DB[17:9]
1	0	1	3-line 9bit serial I/F II	SDA: in SDO: out
1	1	0	4-line 8bit serial I/F II	SDA: in SDO: out

**9. Block Diagram:**



## 10. Backlight:

1. Standard Lamp Styles (Edge Lighting Type):  
The LED chips are distributed over the edge light area of the illumination unit, which gives the less power consumption:
2. The Main Advantages of the LED Backlight are as following:
  - 2.1 The brightness of the backlight can simply be adjusted.  
By a resistor or a potentiometer.

### 3. Data About LED Backlight:

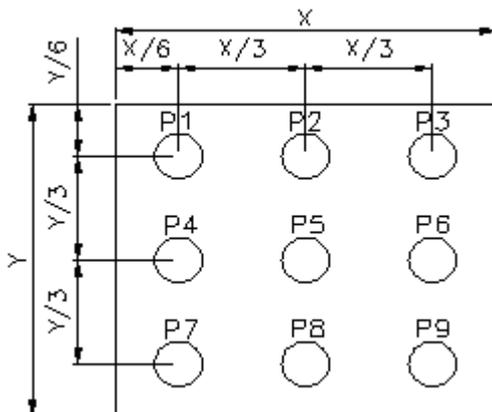
(Ta=25°C)

PARAMETER	Sym.	Min.	Typ.	Max.	Unit	Test Condition	Note
Supply Current	I	-	60	-	mA	V=3.2	
Supply Voltage	V	2.7	3.2	3.5	V	If=60mA	
Luminous Intensity for LCM	IV	260	320	-	Cd/m <sup>2</sup>		2
Uniformity for LCM	-	70	-	-	%		3
Life Time	-	20000	-	-	Hr.		4
Color	White						

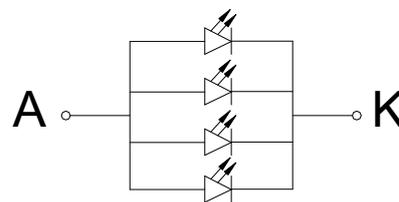
NOTE:

1. Backlight Only
2. Average Luminous Intensity of P1-P9
3. Uniformity = Min/Max \* 100%
4. LED life time defined as follows: The final brightness is at 50% of original brightness

#### Measured Method: (X\*Y: Light Area)



#### Internal Circuit Diagram



#### (Effective spatial Distribution)

Using aperture of 1°, distance 50cm.

## **11. Standard Specification for Reliability:**

### 11-1. Standard Specifications for Reliability of LCD Module

No	Item	Description
01	High temperature operation	The sample should be allowed to stand at 70°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
02	Low temperature operation	The sample should be allowed to stand at -20°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
03	High temperature storage	The sample should be allowed to stand at 80°C for 240 hours under no-load condition, and then returning it to normal temperature condition, and allowing it stand for 2 hours.
04	Low temperature storage	The sample should be allowed to stand at -30°C for 240 hours under no-load condition, then returning it to normal temperature condition, and allowing it stand for 2 hours.
05	Moisture storage	The sample should be allowed to stand at 60°C,90%RH MAX for 240 hours under no-load condition, then taking it out and drying it at normal temperature for 2 hours.
06	Thermal shock storage	The sample should be allowed to stand the following 10 cycles : -30°C for 30 minutes → normal temperature for 5 minutes → +80°C for 30 minutes → normal temperature for 5 minutes, as one cycle.
07	Packing vibration	Frequency range : 10Hz ~ 55Hz Amplitude of vibration : 1.5mm      Sweep time: 12 min X,Y,Z 2 hours for each direction.
08	Packing drop test	According to ISTA 1A 2001.
09	Electrical Static Discharge	Air: ±4KV 150pF/330Ω 5 times
		Contact: ±2KV 150pF/330Ω 5 time

\*Sample size for each test item is 3~5pcs

## 11 - 2. Testing Conditions and Inspection Criteria

For the final test the testing sample must be stored at room temperature for 24 hours, after the tests listed in Table 11-1, Standard specifications for Reliability have been executed in order to ensure stability.

No	Item	Test Model	In section Criteria
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

## 11- 3. MTBF

MTBF	Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature ( $25\pm 5^{\circ}\text{C}$ ), normal humidity ( $50\pm 10\%$ RH), and in area not exposed to direct sun light.
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## **12. Specification of Quality Assurance:**

### 12-1. Purpose

This standard for Quality Assurance should affirm the quality of LCD module products to supply to purchaser by YEEBO CORPORATION (Supplier).

### 12-2. Standard for Quality Test

#### a. Inspection:

Before delivering, the supplier should take the following tests, and affirm the quality of product.

#### b. Electro-Optical Characteristics:

According to the individual specification to test the product.

#### c. Test of Appearance Characteristics:

According to the individual specification to test the product.

#### d. Test of Reliability Characteristics:

According to the definition of reliability on the specification for testing products.

#### e. Delivery Test:

Before delivering, the supplier should take the delivery test.

(i) Test method: According to ISO2859-1. General Inspection Level II take a single time.

(ii) The defects classify of AQL as following:

Major defect: AQL = 0.65

Minor defect: AQL = 2.5

Total defects: AQL = 2.5

### 12-3. Non- conforming Analysis & Deal With Manners

#### a. Non- conforming Analysis:

(i) Purchaser should supply the detail data of non- conforming sample and the non- conforming.

(ii) After accepting the detail data from purchaser, the analysis of non- conforming should be finished in two weeks.

(iii) If supplier can not finish analysis on time, must announce purchaser before 3 days.

#### b. Disposition of non- conforming:

(i) If find any product defect of supplier during assembly time, supplier must change the good product for every defect after recognition.

(ii) Both supplier and customer should analyze the reason and discuss the disposition of non- conforming when the reason of nonconforming is not sure.

### 12-4. Agreement items

Both sides should discuss together when the following problems happen.

a. There is any problem of standard of quality assurance, and both sides should think that must be modified.

b. There is any argument item which does not record in the standard of quality assurance.

c. Any other special problem.

12-5. Standard of The Product Appearance Test

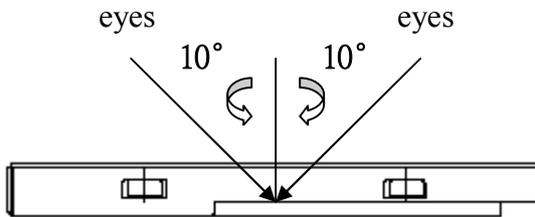
a. Manner of appearance test:

(i) The test must be under  $20W \times 2$  or  $40W$  fluorescent light, and the distance of view must be at  $30 \pm 5cm$ .

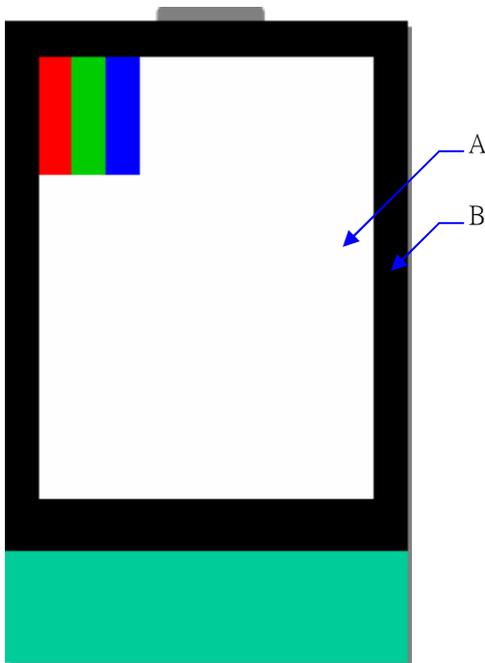
(ii) When test the model of transmissive product must add the reflective plate.

(iii) The test direction is base on around  $10^\circ$  of vertical line.

(iii) Temperature:  $25 \pm 5^\circ C$  Humidity:  $60 \pm 10\%RH$



(iv) Definition of area:



A. Area: Viewing area.

B. Area: Out of viewing area.

(Outside viewing area)

b. Basic principle:

(i) It will accord to the AQL when the standard can not be described.

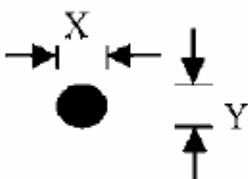
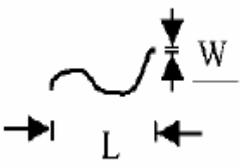
(ii) The sample of the lowest acceptable quality level must be discussed by both supplier and customer when any dispute happened.

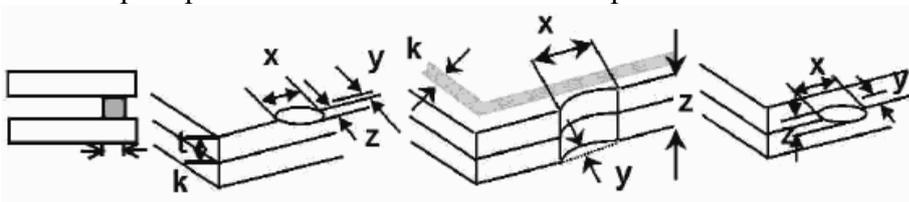
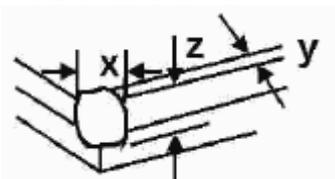
(iii) Must add new item on time when it is necessary.

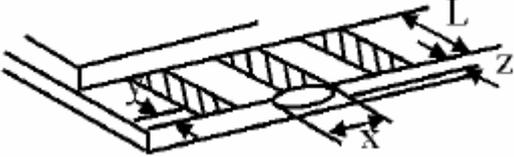
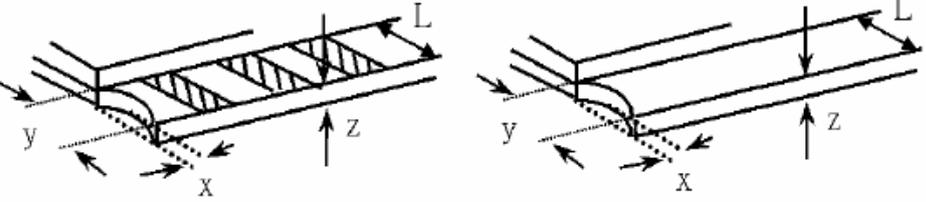
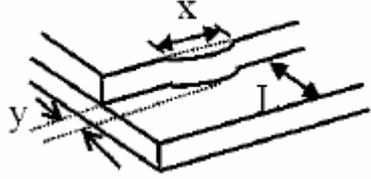
c. Standard of inspection: (Unit: mm)

12-6. Inspection specification

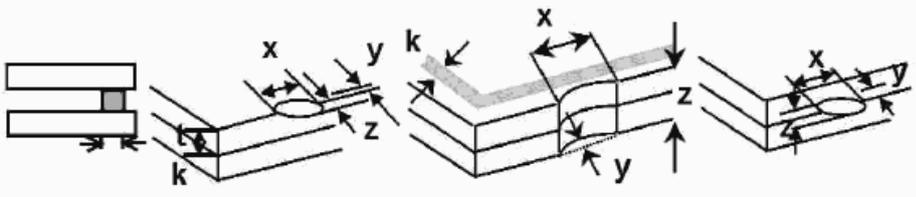
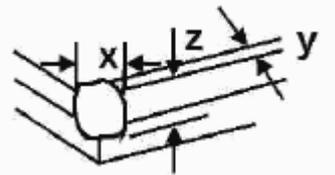
Defect out of viewing area can be neglected.

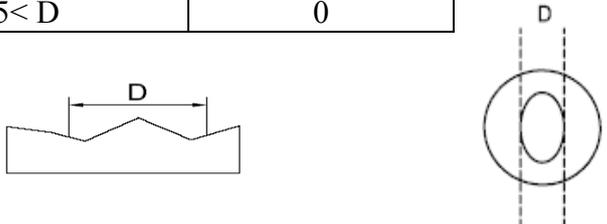
NO	Item	Criterion	AQL												
01	Electrical Testing	1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Flicker	0.65												
02	Black or White spots or Bright spots or Color spots on LCD (Display only)	2.1 White and black or color spots on display $\leq 0.25\text{mm}$ , no more than Five spots. 2.2 Densely spaced: No more than three spots within 3mm. 2.3 Not visible through 5% ND filter	2.5												
03	LCD and Touch Panel black spots, white spots, contamination (non – display)	3.1 Round type: As following drawing $\Phi = (X+Y) / 2$  <table border="1" data-bbox="817 990 1350 1240"> <thead> <tr> <th>Size(mm)</th> <th>Acceptable Q'ty</th> </tr> </thead> <tbody> <tr> <td><math>\Phi \leq 0.10</math></td> <td>Accept no dense</td> </tr> <tr> <td><math>0.10 &lt; \Phi \leq 0.20</math></td> <td>2</td> </tr> <tr> <td><math>0.20 &lt; \Phi \leq 0.25</math></td> <td>2</td> </tr> <tr> <td><math>0.25 &lt; \Phi \leq 0.30</math></td> <td>1</td> </tr> <tr> <td><math>0.30 &lt; \Phi</math></td> <td>0</td> </tr> </tbody> </table> <p>* Densely spaced: No more than two spots within 3mm.</p>	Size(mm)	Acceptable Q'ty	$\Phi \leq 0.10$	Accept no dense	$0.10 < \Phi \leq 0.20$	2	$0.20 < \Phi \leq 0.25$	2	$0.25 < \Phi \leq 0.30$	1	$0.30 < \Phi$	0	2.5
		Size(mm)	Acceptable Q'ty												
$\Phi \leq 0.10$	Accept no dense														
$0.10 < \Phi \leq 0.20$	2														
$0.20 < \Phi \leq 0.25$	2														
$0.25 < \Phi \leq 0.30$	1														
$0.30 < \Phi$	0														
3.2 Line type: (As following drawing)  <table border="1" data-bbox="721 1393 1350 1668"> <thead> <tr> <th>Length(mm)</th> <th>Width(mm)</th> <th>Acceptable Q'ty</th> </tr> </thead> <tbody> <tr> <td>---</td> <td><math>W \leq 0.02</math></td> <td>Accept no dense</td> </tr> <tr> <td><math>L \leq 3.0</math></td> <td><math>0.02 &lt; W \leq 0.05</math></td> <td rowspan="2">2</td> </tr> <tr> <td><math>L \leq 2.5</math></td> <td><math>0.03 &lt; W \leq 0.08</math></td> </tr> <tr> <td>---</td> <td><math>0.08 &lt; W</math></td> <td>Rejection</td> </tr> </tbody> </table> <p>* Densely spaced: No more than two lines within 3mm.</p>	Length(mm)	Width(mm)	Acceptable Q'ty	---	$W \leq 0.02$	Accept no dense	$L \leq 3.0$	$0.02 < W \leq 0.05$	2	$L \leq 2.5$	$0.03 < W \leq 0.08$	---	$0.08 < W$	Rejection	2.5
Length(mm)	Width(mm)	Acceptable Q'ty													
---	$W \leq 0.02$	Accept no dense													
$L \leq 3.0$	$0.02 < W \leq 0.05$	2													
$L \leq 2.5$	$0.03 < W \leq 0.08$														
---	$0.08 < W$	Rejection													

NO	Item	Criterion	AQL																		
04	Polarizer bubbles	<p>If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction</p> <table border="1"> <thead> <tr> <th>Size <math>\Phi</math>(mm)</th> <th>Acceptable Q'ty</th> </tr> </thead> <tbody> <tr> <td><math>\Phi \leq 0.20</math></td> <td>Accept no dense</td> </tr> <tr> <td><math>0.20 &lt; \Phi \leq 0.50</math></td> <td>3</td> </tr> <tr> <td><math>0.50 &lt; \Phi \leq 1.00</math></td> <td>2</td> </tr> <tr> <td><math>1.00 &lt; \Phi</math></td> <td>0</td> </tr> <tr> <td>Total Q'ty</td> <td>3</td> </tr> </tbody> </table>	Size $\Phi$ (mm)	Acceptable Q'ty	$\Phi \leq 0.20$	Accept no dense	$0.20 < \Phi \leq 0.50$	3	$0.50 < \Phi \leq 1.00$	2	$1.00 < \Phi$	0	Total Q'ty	3	2.5						
Size $\Phi$ (mm)	Acceptable Q'ty																				
$\Phi \leq 0.20$	Accept no dense																				
$0.20 < \Phi \leq 0.50$	3																				
$0.50 < \Phi \leq 1.00$	2																				
$1.00 < \Phi$	0																				
Total Q'ty	3																				
05	Scratches	Follow NO.3 -2 Line Type.																			
06	Mura	Not visible through 5% ND filter in 50% gray.	2.5																		
07	Chipped glass	<p>Symbols:  x: Chip length                      y: Chip width                      z: Chip thickness  k: Seal width                      t: Glass thickness                      a: LCD side length  L: Electrode pad length</p> <p>7.1 General glass chip:  7.1.1 Chip on panel surface and crack between panels:</p>  <table border="1"> <thead> <tr> <th>z: Chip thickness</th> <th>y: Chip width</th> <th>x: Chip length</th> </tr> </thead> <tbody> <tr> <td><math>Z \leq 1/2t</math></td> <td>Not over viewing area</td> <td><math>x \leq 1/8a</math></td> </tr> <tr> <td><math>1/2t &lt; z \leq 2t</math></td> <td>Not exceed 1/3k</td> <td><math>x \leq 1/8a</math></td> </tr> </tbody> </table> <p>⊙ Unit: mm  ⊙ If there are 2 or more chips, x is the total length of each chip</p> <p>7.1.2 Corner crack:</p>  <table border="1"> <thead> <tr> <th>z: Chip thickness</th> <th>y: Chip width</th> <th>x: Chip length</th> </tr> </thead> <tbody> <tr> <td><math>Z \leq 1/2t</math></td> <td>Not over viewing area</td> <td><math>x \leq 1/8a</math></td> </tr> <tr> <td><math>1/2t &lt; z \leq 2t</math></td> <td>Not exceed 1/3k</td> <td><math>x \leq 1/8a</math></td> </tr> </tbody> </table> <p>⊙ Unit: mm  ⊙ If there are 2 or more chips, x is the total length of each chip</p>	z: Chip thickness	y: Chip width	x: Chip length	$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$	$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$	z: Chip thickness	y: Chip width	x: Chip length	$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$	$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$	2.5
z: Chip thickness	y: Chip width	x: Chip length																			
$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$																			
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NO	Item	Criterion	AQL																
08	Glass crack	<p>Symbols:            x: Chip length            y: Chip width            z: Chip thickness            k: Seal width            t: Glass thickness    a: LCD side length            L: Electrode pad length</p> <p>8.1 Protrusion over terminal:            8.1.1 Chip on electrode pad:</p>  <table border="1" data-bbox="544 685 1230 842"> <tr> <td>y: Chip width</td> <td>x: Chip length</td> <td>z: Chip thickness</td> </tr> <tr> <td><math>y \leq 0.5\text{mm}</math></td> <td><math>x \leq 1/8a</math></td> <td><math>0 &lt; z \leq t</math></td> </tr> </table> <p>8.1.2            Non-conductive portion:</p>  <table border="1" data-bbox="544 1205 1230 1361"> <tr> <td>y: Chip width</td> <td>x: Chip length</td> <td>z: Chip thickness</td> </tr> <tr> <td><math>y \leq L</math></td> <td><math>x \leq 1/8a</math></td> <td><math>0 &lt; z \leq t</math></td> </tr> </table> <p>⊙ If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.            ⊙ If the product will be heat sealed by the customer, the alignment mark must not be damaged.</p> <p>8.1.3 Substrate protuberance and internal crack</p>  <table border="1" data-bbox="863 1675 1305 1832"> <tr> <td>y: width</td> <td>x: length</td> </tr> <tr> <td><math>y \leq 1/3L</math></td> <td><math>X \leq a</math></td> </tr> </table>	y: Chip width	x: Chip length	z: Chip thickness	$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$	y: Chip width	x: Chip length	z: Chip thickness	$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$	y: width	x: length	$y \leq 1/3L$	$X \leq a$	2.5
y: Chip width	x: Chip length	z: Chip thickness																	
$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$																	
y: Chip width	x: Chip length	z: Chip thickness																	
$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$																	
y: width	x: length																		
$y \leq 1/3L$	$X \leq a$																		

NO	Item	Criterion	AQL
09	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
10	Backlight elements	10.1 Illumination source flickers when lit. 10.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 10.3 Backlight doesn't light or color is wrong.	2.5 2.5 0.65
11	Bezel	Bezel must comply with product specifications.	2.5
12	PCB、COB	12.1 COB seal may not have pinholes larger than 0.2mm or contamination. 12.2 COB seal surface may not have pinholes through to the IC. 12.3 The height of the COB should not exceed the height indicated in the assembly diagram. 12.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 12.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 12.6 The jumper on the PCB should conform to the product characteristic chart.	2.5 2.5 2.5 2.5 0.65 0.65
13	FPC	13.1 FPC terminal damage $\leq$ 1/2 FPC terminal width and can not affect the function , we judge accept. 13.2 FPC alignment hole damage $\leq$ 1/2 alignment area and can not affect the function , we judge accept.	2.5 2.5
14	Soldering	14.1 No cold solder joints, missing solder connections, oxidation or icicle. 14.2 No short circuits in components on PCB or FPC.	2.5 0.65

NO	Item	Criterion	AQL												
15	Touch Panel Chipped glass	<p>Symbols:  x: Chip length                      y: Chip width                      z: Chip thickness  k: Seal width                      t: Touch Panel Total thickness    a: LCD side length  L: Electrode pad length</p> <p>15.1 General glass chip:  15.1.1 Chip on panel surface and crack between panels:</p>  <table border="1" data-bbox="400 801 1220 1019"> <tr> <td>z: Chip thickness</td> <td>y: Chip width</td> <td>x: Chip length</td> </tr> <tr> <td><math>Z \leq t</math></td> <td><math>\leq 1/2 k</math> and not over viewing area</td> <td><math>x \leq 1/8a</math></td> </tr> </table> <p>⊙ Unit: mm  ⊙ If there are 2 or more chips, x is the total length of each chip</p> <p>15.1.2 Corner crack:</p>  <table border="1" data-bbox="400 1400 1220 1617"> <tr> <td>z: Chip thickness</td> <td>y: Chip width</td> <td>x: Chip length</td> </tr> <tr> <td><math>z \leq t</math></td> <td><math>\leq 1/2 k</math> and not over viewing area</td> <td><math>x \leq 1/8a</math></td> </tr> </table> <p>⊙ Unit: mm  ⊙ If there are 2 or more chips, x is the total length of each chip</p>	z: Chip thickness	y: Chip width	x: Chip length	$Z \leq t$	$\leq 1/2 k$ and not over viewing area	$x \leq 1/8a$	z: Chip thickness	y: Chip width	x: Chip length	$z \leq t$	$\leq 1/2 k$ and not over viewing area	$x \leq 1/8a$	2.5
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NO	Item	Criterion	AQL										
16	Touch Panel(Fish eye、dent and bubble on film)	<table border="1"> <thead> <tr> <th>SIZE(mm)</th> <th>Acceptable Q'ty</th> </tr> </thead> <tbody> <tr> <td><math>\Phi \leq 0.2</math></td> <td>Accept no dense</td> </tr> <tr> <td><math>0.2 &lt; D \leq 0.4</math></td> <td>5</td> </tr> <tr> <td><math>0.4 &lt; D \leq 0.5</math></td> <td>2</td> </tr> <tr> <td><math>0.5 &lt; D</math></td> <td>0</td> </tr> </tbody> </table> 	SIZE(mm)	Acceptable Q'ty	$\Phi \leq 0.2$	Accept no dense	$0.2 < D \leq 0.4$	5	$0.4 < D \leq 0.5$	2	$0.5 < D$	0	2.5
SIZE(mm)	Acceptable Q'ty												
$\Phi \leq 0.2$	Accept no dense												
$0.2 < D \leq 0.4$	5												
$0.4 < D \leq 0.5$	2												
$0.5 < D$	0												
17	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion( $\leq 2.5\%$ ) , it is acceptable.	2.5										
18	Touch Panel Linearity	Less than 2.5% is acceptable.	2.5										
19	LCD Ripple	Touch the touch panel , can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g	2.5										
20	General appearance	20.1 Pin type must match type in specification sheet. 20.2 LCD pin loose or missing pins. 20.3 Product packaging must the same as specified on packaging specification sheet. 20.4 Product dimension and structure must conform to product specification sheet.	0.65 0.65 0.65 0.65										

## **13. Handling Precaution:**

### 13-1 Handling of LCM

- Don't give external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance. Must not lick and swallow. when the liquid is attach to your hand, skin, cloth etc. Wash it out thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should be grounded whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.

### 13-2 Storage

- Store in an ambient temperature of  $25\pm 10^{\circ}\text{C}$ , and in a relative humidity of  $50\pm 10\%\text{RH}$ . Don't expose to sunlight or fluorescent light.
- Storage in a clean environment, free from dust, active gas, and solvent.
- Store in anti-static electricity container.
- Store without any physical load.

### 13-3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: No higher than  $280\pm 10^{\circ}\text{C}$  and less than 3 sec during Hand soldering.
- Rewiring: no more than 2 times.

## **14. Guarantee:**

Our products meet requirements of the environment.  
YEEBO ROHS requirement is based on European Union Directive 2011/65/EU (ROHS) Requirements and Update.